ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC, Bannockl	burn, Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the s encompasse	ubstances es all lowe	within the man r level materials	ufacturer lis s for which	sted item. Note: the manufacture	if the item is an a r has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat					ion			
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority				Res	Response Date*			
semi											2025-06-07			
Contact Name	t Name Title - Contact					Phone - Contact*				Em	Email - Contact*			
Product-Env-Stewards	oduct-Env-Stewards Product Envir			viro Compliance			NA				Product-Env-Stewards@onsemi.com			
uthorized Representative* Title - Representa			intative		Phone - Representative*			Em	Email - Representative*					
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Pr	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		mber Mfr Item Name			Effective Dat	e Version	1	Manufacturing Site		Weight*	UOM	Unit Type	
	NVMYS G	VMYS1D3N04CTW Trench 6 40V		' SL NFET		2025-06-07		1	РВВ		74.911	mg	Each	
Aanufacturing Proccess Informa	tion													
Terminal Plating / Grid Array Ma	aterial	Ferminal Base A	Alloy	J-STD-020 MSL Rating		Peak Pro	eak Process Body Temperature		re Max Time a	t Peak Tem	perature Num	ber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	s	seconds 3				
omments														
vel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	3.7	mg	Supplier	Iron (Fe)	7439-89-6		0.0044	mg
			Supplier	Copper (Cu)	7440-50-8		3.6944	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0011	mg
Die	0.5	mg	Supplier	Silicon (Si)	7440-21-3		0.5	mg
Lead Frame	33.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0033	mg
			Supplier	Iron (Fe)	7439-89-6		0.0401	mg
			Supplier	Copper (Cu)	7440-50-8		33.3466	mg
			Supplier	Phosphorus (P)	7723-14-0		0.01	mg
Mold Compound-Black	31.9	mg	Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.1595	mg
			Supplier	Boron zinc hydroxide oxide	138265-88-0		4.785	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.785	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0797	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.3363	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.7545	mg
lating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Solder Paste	3.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0925	mg
			А	Lead (Pb)	7439-92-1	7a	3.4225	mg
			Supplier	Tin (Sn)	7440-31-5		0.185	mg
Wire Bond - Cu	0.011	mg	Supplier	Copper (Cu)	7440-50-8		0.011	mg